



LTM8061 77LD 15mm X 9mm X 4.32mm - Epoxy (DA) (TABLE OF MATERIAL DECLARATION)

The LTM8061 is RoHS compliant per EU RoHS Directive 2015/863/EU.

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

| No. | Part Name | Material Name | Component Weight (gram) | Materials Analysis (element) | CAS Number | Material Mass (gram) | Materials Analysis (weight %) |
|-----------------------------|---------------------------|---------------|-------------------------|--|--|----------------------|-------------------------------|
| 1 | Substrate | Circuit Board | 0.1399 | Barium Compounds | 7727-43-7 | 0.00378 | 2.70 |
| | | | | BT Resin/Filler (Silica Crystalline) | 105391-33-1, 1156-51-0/9003-36-5/21645-51-2 | 0.05053 | 36.12 |
| | | | | Copper Metal | 7440-50-8 | 0.03484 | 24.90 |
| | | | | Copper Compounds | 147-14-8 | 0.00003 | 0.02 |
| | | | | Ecotoxic substances | 7440-38-2, 7440-28-0 | 0.00000 | 0.00 |
| | | | | Gold metal or alloy | 7440-57-5 | 0.00046 | 0.33 |
| | | | | Nickel | 7440-02-0 | 0.00213 | 1.52 |
| | | | | Zinc | 7440-66-6 | 0.00004 | 0.03 |
| | | | | Continuous Filament Fiber Glass | 65997-17-3 | 0.03970 | 28.38 |
| | | | | Acrylic Resin | non-disclosure | 0.00719 | 5.14 |
| | | | | Epoxy Resin | non-disclosure | 0.00003 | 0.02 |
| | | | | Chromium(III) Oxide | 1308-38-9 | 0.00000 | 0.00 |
| | | | | Silica amorphous | 7631-86-9 | 0.00008 | 0.06 |
| | | | | Talc;not containing fibers like asbestos | 14807-96-9 | 0.00043 | 0.31 |
| | | | | Aromatic Carbonyl compounds | non-disclosure | 0.00041 | 0.29 |
| | | | | Cyanoguanidine | 461-58-5 | 0.00001 | 0.01 |
| | | | | Calcium caobonate | 471-34-1 | 0.00001 | 0.00 |
| Amine compounds | non-disclosure | 0.00005 | 0.04 | | | | |
| Leveling agent and others | non-disclosure | 0.00017 | 0.12 | | | | |
| 2 | Solder Paste | Alloy | 0.0017 | Sn | 7440-31-5 | 0.00160 | 95.00 |
| | | | | Sb | 7440-36-0 | 0.00008 | 5.00 |
| 3 | Epoxy | | 0.0012 | Di-ester resin | non-disclosure | 0.00012 | 10.00 |
| | | | | Functionalized ester | non-disclosure | 0.00012 | 10.00 |
| | | | | Silver | 7440-22-4 | 0.00096 | 80.00 |
| 4 | Passive/Active Components | | 0.7177 | Iron Powder (Fe) | 7439-89-6 | 0.43297 | 60.32 |
| | | | | Copper (Cu) | 7440-50-8 | 0.25202 | 35.11 |
| | | | | Nickel (Ni) | 7440-02-0 | 0.00535 | 0.75 |
| | | | | Tin (Sn) | 7440-31-5 | 0.00202 | 0.28 |
| | | | | Ceramic (Ba Compounds) | 12047-27-7 | 0.02541 | 3.54 |
| 5 | Active Ics | Silicon | 0.0033 | Silicon | 7440-21-3 | 0.00325 | 100.00 |
| 6 | Wire | Gold | 0.0155 | Au | 7440-57-5 | 0.01550 | 99.99 |
| 7 | Encapsulation | Epoxy Resin | 0.8186 | Fused Silica | 60676-86-0 | 0.63193 | 77.20 |
| | | | | Epoxy Resin | non-disclosure | 0.07285 | 8.90 |
| | | | | Phenol Resin | non-disclosure | 0.07285 | 8.90 |
| | | | | Crytalline Silica | 14808-60-7 | 0.02456 | 3.00 |
| | | | | Carbon Black | 1333-86-4 | 0.00409 | 0.50 |
| | | | | Metal Hydroxide | non-disclosure | 0.01228 | 1.50 |
| Total Package Weight | | | 1.6979 | | | | |

Note: Composition derived from MSDS and material C of C from Vendors
Component Weight based on assembly of generic parts